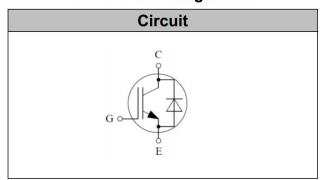


**TO-3P Pin Configuration** 



### **IGBT** Discrete

$\mathbf{V}_{ ext{CE}}$	650	V
$\mathbf{I}_{\mathbf{C}}$	40	A
V <sub>CE(SAT)</sub> I <sub>C</sub> =40A	1.6	V

### **Applications**

- · High-frequency converters
- · AC and DC servo drive amplifier
- · Induction heating

#### **Features**

- High breakdown voltage to 650V for improved reliability
- Maximum junction temperature 175<sup>°</sup>C
- · Positive temperature coefficient
- · Resonant converters
- · Induction heating

**Maximum Ratings** 

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	$V_{CE}$	650	V
DC Collector Current, limited by $T_{jmax}$ $T_C=25^{\circ}C$ $T_C=100^{\circ}C$	$I_{\mathrm{C}}$	80 40	A
Diode Forward Current, limited by $T_{jmax}$ $T_C = 25$ °C $T_C = 100$ °C	$I_{\mathrm{F}}$	80 40	A
Continuous Gate-Emitter Voltage	$V_{GE}$	±20	V
Pulsed Collector Current, $V_{GE}$ =15V, tp limited by $T_{jmax}$	Ісм	160	A
Power Dissipation , Tj=175°C,Tc=25°C	$P_{tot}$	246	W
Operating Junction Temperature	T <sub>j</sub>	-40+175	°C
Storage Temperature	$T_{s}$	-55+150	°C
Soldering Temperature, wave soldering 1.6mm(0.063in.) from case for 10s	-	260	°C

Rev.1.0



### **Thermal Resistance**

Parameter	Symbol	Max. Value	Unit
IGBT Thermal Resistance, Junction - Case	$R_{th}(j-c)$	0.61	K/W
Diode Thermal Resistance, Junction - Case	$R_{th}(j-c)$	0.68	K/W
Thermal Resistance, Junction - Ambient	R <sub>th</sub> (j-a)	40	K/W

# **Electrical Characteristics of the IGBT** $(T_j=25^{\circ}Cunless otherwise specified)$ :

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	V <sub>GE</sub> =0V, I <sub>C</sub> =250μA	650	-	-	V
Gate Threshold Voltage	$V_{\text{GE(th)}}$	$V_{GE}=V_{CE}, I_{C}=250\mu A$	4.5	5.5	6.5	V
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$V_{GE}=15V, I_{C}=40A$ $T_{j}=25^{\circ}C,$ $T_{j}=150^{\circ}C$	-	1.6 2.1	2.05	V
Zero Gate Voltage Collector Current	I <sub>CES</sub>	V <sub>CE</sub> =650V, V <sub>GE</sub> =0V T <sub>j</sub> = 25°C, T <sub>i</sub> =150°C		-	15 300	uA
Gate-Emitter Leakage Current	I <sub>GES</sub>	$V_{CE}$ = 0V, $V_{GE}$ = ± 20V	-	-	100	nA
Input Capacitance	Cies		-	1920	-	
Output Capacitance	Coes	$V_{CE}$ = 25V, $V_{GE}$ = 0V, $f$ = 1MHz	-	100	-	pF
Reverse Transfer Capacitance	C <sub>res</sub>		-	32	-	
Gate Charge	$Q_G$		-1	127	-	
Gate-Emitter Charge	Q <sub>GE</sub>	V <sub>CC</sub> =40V,I <sub>C</sub> =40A, V <sub>GE</sub> =15V	-	15	-	nC
Gate-Collector Charge	Q <sub>GC</sub>		-	37	-	



# Switching Characteristic, Inductive Load (T<sub>j</sub>= 25°C unless otherwise specified):

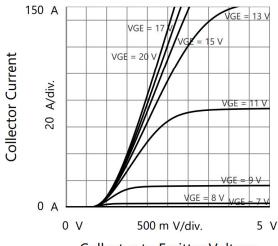
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Turn-on Delay Time	t <sub>d(on)</sub>		-	26	-	ns
Rise Time	t <sub>r</sub>		-	35	-	ns
Turn-on Energy	Eon	$V_{CC} = 400V, I_{C} = 40A,$ $V_{GE} = 15V$	-	1.05	-	mJ
Turn-off Delay Time	$t_{d(off)}$	$R_g=10\Omega$	-	110	-	ns
Fall Time	$t_{\mathrm{f}}$		-	14	-	ns
Turn-off Energy	E <sub>off</sub>		-	0.32	-	mJ

## **Electrical Characteristics of the DIODE** $(T_j=25^{\circ}Cunless otherwise specified)$ :

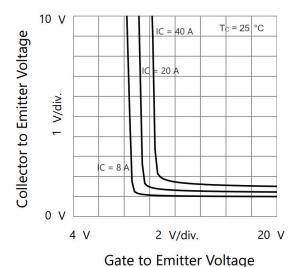
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Diode Forward Voltage	$V_{F}$	$I_F = 40A$	-	1.75	-	V
Reverse Recovery Time	$T_{rr}$	I <sub>F</sub> =40A, V <sub>R</sub> =400V, di/dt=-100A/μs,	-	80	-	ns
Reverse Recovery Charge	Qrr		-	839	-	nC

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

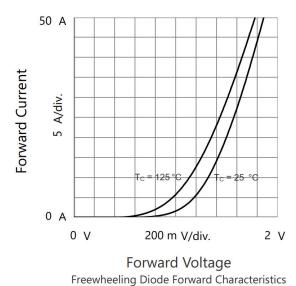
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Collector to Emitter Voltage Output Characteristics

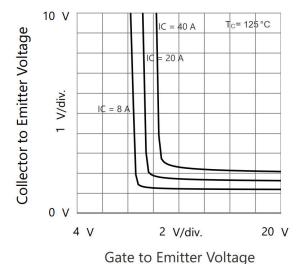


Collector to Emitter Voltage vs. Gate to Emitter Voltage

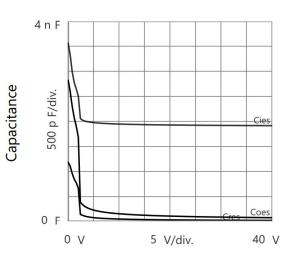


O V 2 V/div. 15 V

Gate to Emitter Voltage Transfer Characteristics



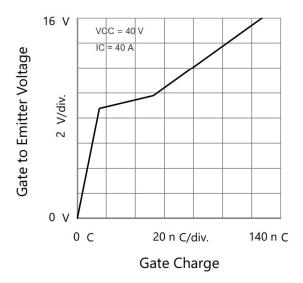
Collector to Emitter Voltage vs. Gate to Emitter Voltage

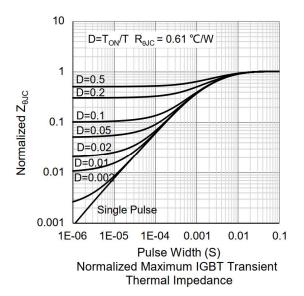


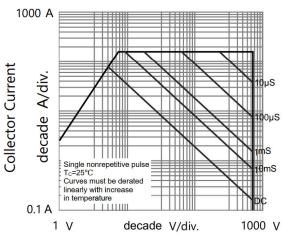
Collector to Emitter Voltage Capacitances



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







Collector to Emitter Voltage SOA Characteristics

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